

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JIANLIN HUANG	11/10/2021
FENG (CARLOS) PAN	11/10/2021
RECEIVING PARTY DATA	
Name:	TYCO ELECTRONICS TECHNOLOGY (SIP) LTD.
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17572758
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NAME OF SUBMITTER:	KERRI J. SMITH
SIGNATURE:	/Kerri J. Smith/
DATE SIGNED:	01/11/2022
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 1	
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COMBINED DECLARATION AND ASSIGNMENT

As a below named and signing inventor, I hereby declare that:

this declaration is directed to inventions and improvements disclosed in:

- ☒ the attached application, or
☐ United States application or PCT international application number _____ filed
on _____,

entitled "**HYBRID ELECTRICAL CONNECTOR AND ELECTRICAL CONNECTOR ASSEMBLY**" ("the APPLICATION");

the APPLICATION was made or authorized to be made by me;

I believe that I am the original inventor or an original joint inventor of a claimed invention in the APPLICATION;

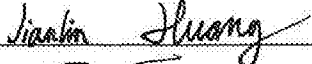
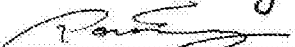
I have reviewed and understand the contents of the APPLICATION, including the claims, and I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. §1.56; and

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.

As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:

TYCO ELECTRONICS TECHNOLOGY (SIP) LTD. ("ASSIGNEE"), a corporation organized and existing under and by virtue of the laws of China, having its principal place of business at #5 Building, 42 Dongfu Road, Suzhou Industrial Park, Suzhou City, Jiangsu Province, China 215126

for a valuable consideration, the receipt of which is hereby acknowledged, **I do hereby sell, assign, transfer, and set over unto the said ASSIGNEE, its successors and assigns**, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries, including all priority rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof; and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment.

Legal Name	Signature	Date
Jianlin HUANG		11/10/21
Feng (Carlos) PAN		2021. 11/10

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